

June 10, 2009

Announcement of Unsecured Straight Bond Issue

Honda Motor Co., Ltd. (hereinafter referred to as the “Company”) issued its 11th Series of Unsecured Straight Bonds as outlined below.

Particulars

The terms and conditions for the issue of its 11th Series of Unsecured Straight Bonds (with limited inter-bond pari passu clause) are as follows:

1	Aggregate amount of the bonds	70 billion yen
2	Denomination of each bond	100 million yen
3	Coupon rate (per annum)	0.759%
4	Issue price	100% of the principal amount
5	Interest payment dates	June 10 and December 10 of each year
6	Maturity date	June 8, 2012
7	Payment date	June 10, 2009
8	Joint lead managers	Nomura Securities Co., Ltd. Mitsubishi UFJ Securities Co., Ltd. Nikko Citigroup Limited Mizuho Securities Co., Ltd.
9	Fiscal agent	The Bank of Tokyo-Mitsubishi UFJ, Ltd.

(Note)

The Company intends to use the proceeds from the bond issue to fund capital expenditures and repayment of loans.

Note: The purpose of this paper is to make a general public announcement concerning the domestic public offering of the Company’s 11th Series of Unsecured Straight Bonds (with limited inter-bond pari passu clause). It has not been prepared for the purpose of an offer of, or solicitation of an offer to buy or subscribe for, securities of the Company.